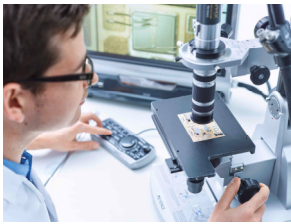


Surface analysis for your electronic assemblies



The functional reliability of electronic assemblies can be significantly impaired by contamination from the production process or from the supply chain. To provide the required evidence of surface cleanliness and therefore of creeping current safety, coatability and bondability, ZESTRON developed some analysis methods.

We offer you:

- Analyses in full compliance with J-STD 001 to qualify the surface cleanliness
- Estimation of the level of cleanliness of your electronic assemblies for coatability, bondability and creeping current safety
- A detailed technical report including documentation and pictures

Basic Analysis Surface Cleanliness*

For an accurate determination or localization of residues from modern fluxes various test methods have to be used to safely analyze your assemblies:

Applied analytical methods	Evidence of
1) Visual inspection using a microscope	Optically visible contaminants as basis for subsequent analyses
2) ZESTRON® Flux Test	Acids that can change the conductivity of your assemblies
3) ZESTRON® Resin Test	Resin residues which e. g. can endanger the adhesion of coatings.
4) Ink Test	Surface tension, which gives information about the wettability of the assembly
5) Ionic contamination measurement, calculated as an equivalent to sodium chloride	Salts that can cause creeping currents, corrosion or electrochemical migration

* At least two assemblies are required for analysis (for ionic contamination measurement: size min. 100 x 100 mm and max. 350 x 250 x 80 mm)

Total Price Basic Analysis (1-5): 341,- Euro without VAT incl. **Technical Report**

Delivery Time: min. 10 working days (quantity depended)

Payment Terms: 14 days 2 % discount or 30 days net

Validity of quotation: 31.12.2020

Our General Terms of Business are to be applied.

Please contact for further information:

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